芯伯乐®
XINBOLE

Product Specification

XBLW SN74LS20

Dual 4-input Nand Gate

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Description

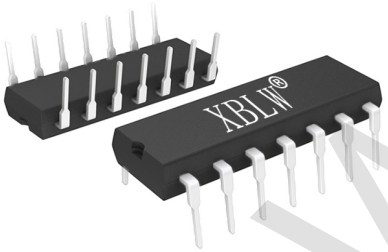
The SN74LS20is a dual 4-input NAND gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

Features

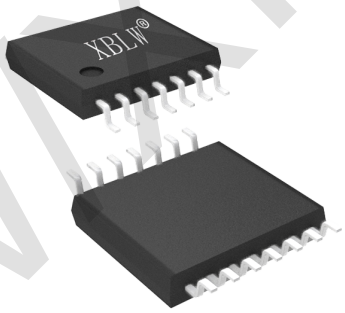
- Buffered inputs
- Wide operating voltage range: 2 V to 6 V
- Specified from -20°C to +85°C
- Packaging information: DIP-14/SOP-14/TSSOP-14

Applications

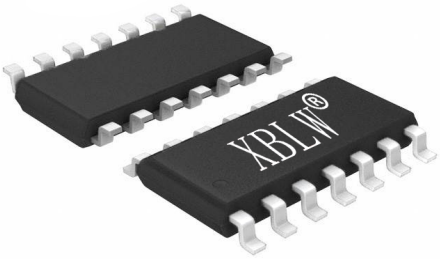
- Alarm / tamper detect circuit
- S-R latch



DIP-14



TSSOP-14



SOP-14

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS20N	DIP-14	74LS20N	Tube	1000Pcs/Box
XBLW SN74LS20DTR	SOP-14	74LS20	Tape	2500Pcs/Reel
XBLW SN74LS20TDTR	TSSOP-14	74LS20	Tape	3000Pcs/Reel

Block Diagram

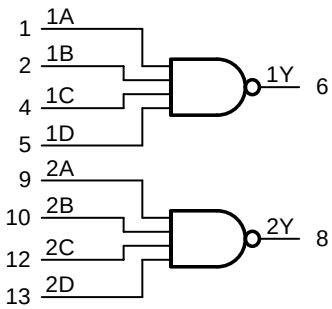


Figure 1. Logic symbol

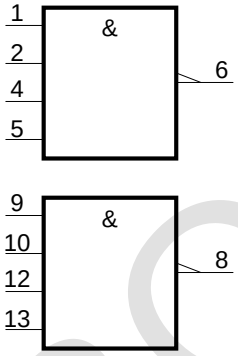


Figure 2. IEC logic symbol

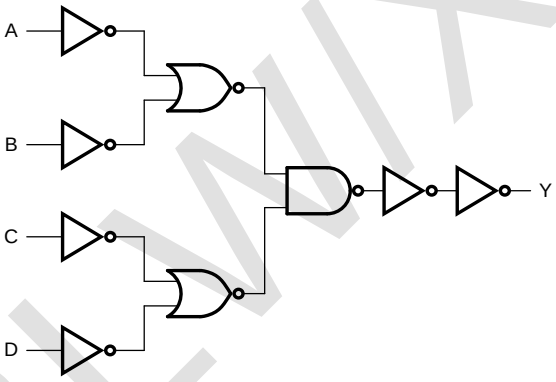


Figure 3. Logic diagram for one gate

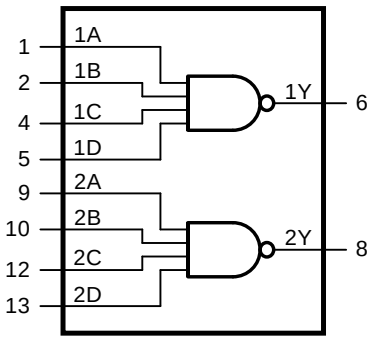
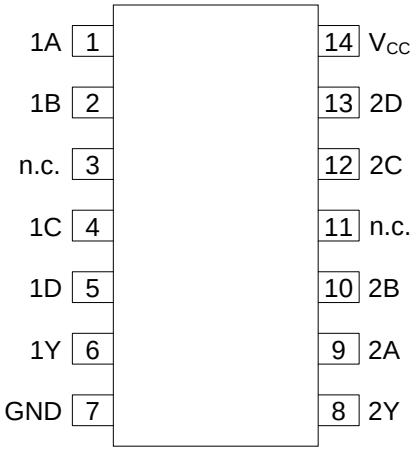


Figure 4. Functional diagram

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	1A	data input
2	1B	data input
3	n.c.	not connected
4	1C	data input
5	1D	data input
6	1Y	data output
7	GND	ground (0V)
8	2Y	data output
9	2A	data input
10	2B	data input
11	n.c.	not connected
12	2C	data input
13	2D	data input
14	V_{CC}	supply voltage

Function Table

Input				Output
nA	**nB**	**nC**	**nD**	**nY**
L	X	X	X	H
X	L	X	X	H
X	X	L	X	H
X	X	X	L	H
H	H	H	H	L

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Max.	Unit
supply voltage	V_{CC}	-		-0.5	+7	V
input clamping current	I_{IK}	V_I<-0.5V or V_I>V_{CC}+0.5V		-	±20	mA
output clamping current	I_{OK}	V_O<-0.5V or V_O>V_{CC}+0.5V		-	±20	mA
output current	I_O	-0.5V<V_O<V_{CC}+0.5V		-	±25	mA
supply current	I_{CC}	-		-	50	mA
ground current	I_{GND}	-		-50	-	mA
total power dissipation	P_{tot}	-		-	500	mW
storage temperature	T_{stg}	-		-65	+150	℃
soldering temperature	T_L	10s	DIP	245		℃
			SOP/TSSOP	260		℃

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	Δt/ΔV	V_{CC}=2.0V	-	-	625	ns/V
		V_{CC}=4.5V	-	1.67	139	ns/V
		V_{CC}=6.0V	-	-	83	ns/V
ambient temperature	T_{amb}	-	-20	-	+85	℃

Electrical Characteristics

DC Characteristics 1

(T_{amb}=25°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	V_{CC}=2.0V		1.5	1.2	-	V
		V_{CC}=4.5V		3.15	2.4	-	V
		V_{CC}=6.0V		4.2	3.2	-	V
LOW-level input voltage	V_{IL}	V_{CC}=2.0V		-	0.8	0.5	V
		V_{CC}=4.5V		-	2.1	1.35	V
		V_{CC}=6.0V		-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	V_I=V_{IH} or V_{IL}	I_O=-20uA; V_{CC}=2.0V	1.9	2.0	-	V
			I_O=-20uA; V_{CC}=4.5V	4.4	4.5	-	V
			I_O=-20uA; V_{CC}=6.0V	5.9	6.0	-	V
			I_O=-4.0mA; V_{CC}=4.5V	3.98	4.32	-	V
			I_O=-5.2mA; V_{CC}=6.0V	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	V_I=V_{IH} or V_{IL}	I_O=20uA; V_{CC}=2.0V	-	0	0.1	V
			I_O=20uA; V_{CC}=4.5V	-	0	0.1	V
			I_O=20uA; V_{CC}=6.0V	-	0	0.1	V
			I_O=4.0mA; V_{CC}=4.5V	-	0.15	0.26	V
			I_O=5.2mA; V_{CC}=6.0V	-	0.16	0.26	V
nput leakage current	I_I	V_I=V_{CC} or GND; V_{CC}=6.0V		-	-	±1	uA
supply current	I_{CC}	V_I=V_{CC} or GND; I_O=0A; V_{CC}=6.0V		-	-	2.0	uA
input capacitance	C_I	-		-	3.5	-	pF

DC Characteristics 2

(T_{amb}=-20°C to +85°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	V_{CC}=2.0V		1.5	-	-	V
		V_{CC}=4.5V		3.15	-	-	V
		V_{CC}=6.0V		4.2	-	-	V
LOW-level input voltage	V_{IL}	V_{CC}=2.0V		-	-	0.5	V
		V_{CC}=4.5V		-	-	1.35	V
		V_{CC}=6.0V		-	-	1.8	V
HIGH-level output voltage	V_{OH}	V_I=V_{IH} or V_{IL}	I_O=-20uA; V_{CC}=2.0V	1.9	-	-	V
			I_O=-20uA; V_{CC}=4.5V	4.4	-	-	V
			I_O=-20uA; V_{CC}=6.0V	5.9	-	-	V
			I_O=-4.0mA; V_{CC}=4.5V	3.84	-	-	V
			I_O=-5.2mA; V_{CC}=6.0V	5.34	-	-	V
LOW-level output voltage	V_{OL}	V_I=V_{IH} or V_{IL}	I_O=20uA; V_{CC}=2.0V	-	-	0.1	V
			I_O=20uA; V_{CC}=4.5V	-	-	0.1	V
			I_O=20uA; V_{CC}=6.0V	-	-	0.1	V
			I_O=4.0mA; V_{CC}=4.5V	-	-	0.33	V
			I_O=5.2mA; V_{CC}=6.0V	-	-	0.33	V
input leakage current	I_I	V_I= V_{CC} or GND; V_{CC}=6.0V		-	-	±1	uA
supply current	I_{CC}	V_I= V_{CC} or GND; I_O=0A; V_{CC}=6.0V		-	-	20	uA

AC Characteristics 1

(T_{amb}=25°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
nA, nB to nY propagation delay	t_{pd}	see Figure 6[1]	V_{CC}=2.0V	-	28	90	ns
			V_{CC}=4.5V	-	10	18	ns
			V_{CC}=5.0V;C_L=15pF	-	8	-	ns
			V_{CC}=6.0V	-	8	15	ns
transition time	t_t	see Figure 6[2]	V_{CC}=2.0V	-	19	75	ns
			V_{CC}=4.5V	-	7	15	ns
			V_{CC}=6.0V	-	6	13	ns
power dissipation capacitance	C_{PD}	per package; V_I=GND to V_{CC}[3]		-	22	-	pF

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] t_t is the same as t_{THL} and t_{TLH}.

[3] C_{PD} isused to determine the dynamic power dissipation (P_D in uW).

$P_D=(C_{PD}\times V_{CC}^2\times f_i\times N)+\Sigma(C_L\times V_{CC}^2\times f_o)$ where: f_i=input frequency in MHz;

f_o=output frequency in MHz;

C_L=output load capacitance in pF; V_{CC}=supply voltage in V;

N=number of inputs switching; $\Sigma(C_L\times V_{CC}^2\times f_o)$=sum of outputs.

AC Characteristics 2

(T_{amb}=-20°C to +85°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
nA, nB to nY propagation delay	t_{pd}	see Figure 6	V_{CC}=2.0V	-	-	115	ns
			V_{CC}=4.5V	-	-	23	ns
			V_{CC}=6.0V	-	-	20	ns
transition time	t_t	see Figure 6	V_{CC}=2.0V	-	-	95	ns
			V_{CC}=4.5V	-	-	19	ns
			V_{CC}=6.0V	-	-	16	ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] t_t is the same as t_{THL} and t_{TLH}.

Measurement Points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
SN74LS20	0.5×V_{CC}	0.5×V_{CC}	0.1×V_{CC}	0.9×V_{CC}

Test Data

Type	Input		Load	Test
	V_I	t_r ,t_f	C_L	
SN74LS20	V_{CC}	6.0ns	15pF, 50pF	t_{PLH}, t_{PHL}

Testing Circuit

AC Testing Circuit

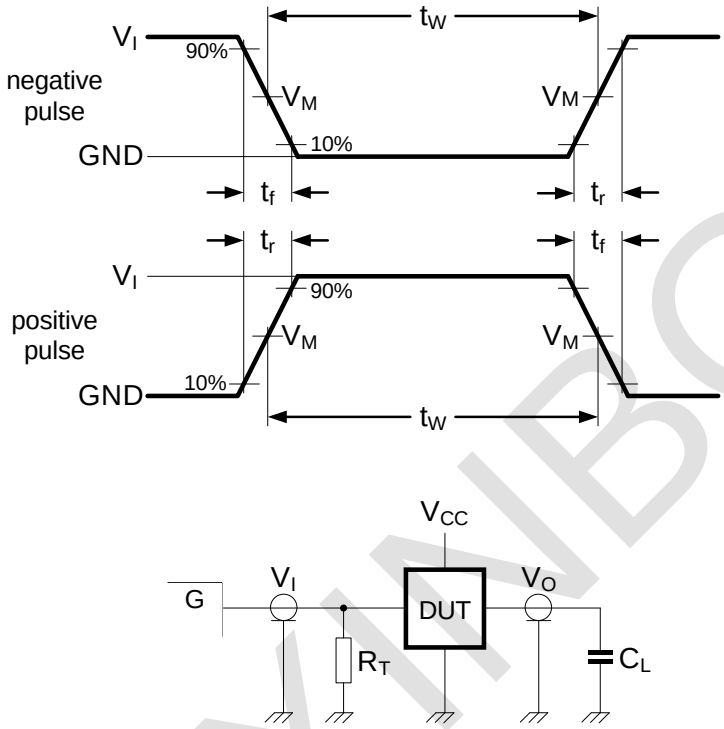


Figure 5. Test circuit for measuring switching times

Definitions for test circuit:
C_L=load capacitance including jig and probe capacitance.
R_T=termination resistance should be equal to the output impedance Z_o of the pulse generator.

AC Testing Waveforms

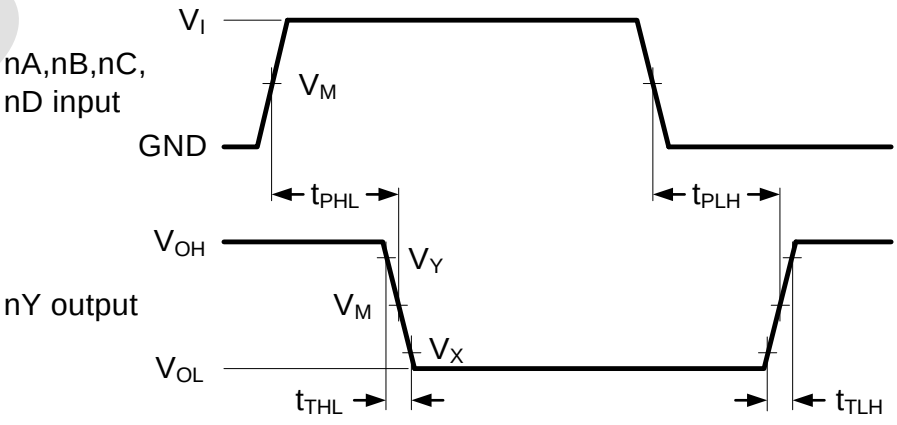
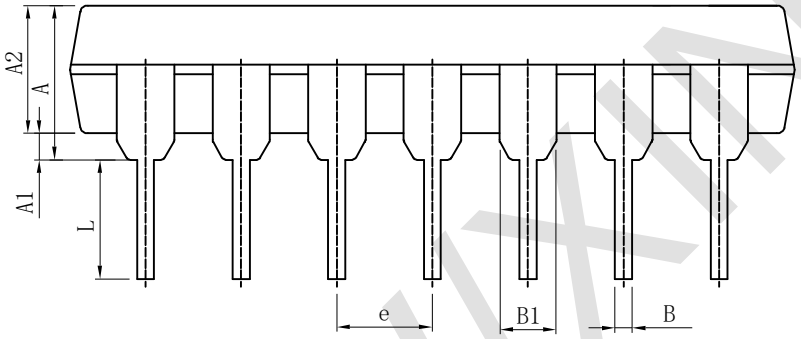


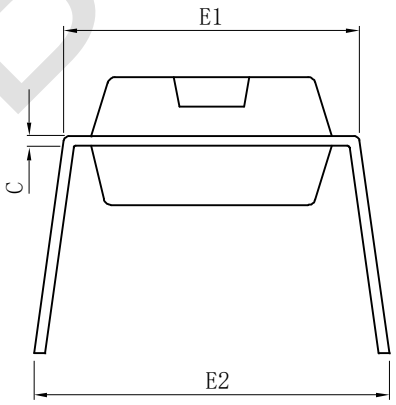
Figure 6. Input to output propagation delays

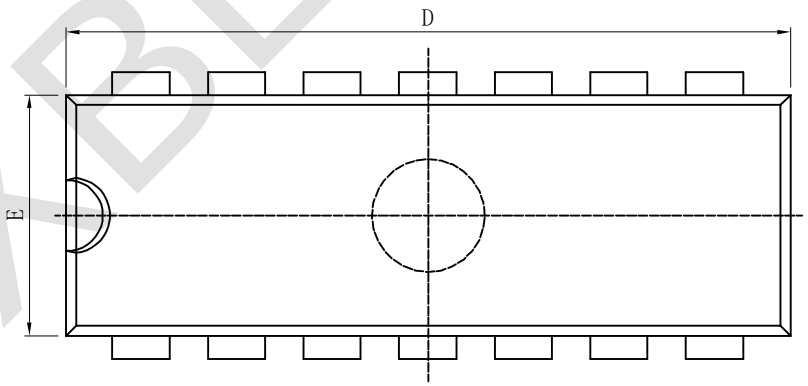
Package Information

· DIP-14

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524(BSC)		B1	0.060(BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.800	19.200	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540(BSC)		e	0.100(BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354

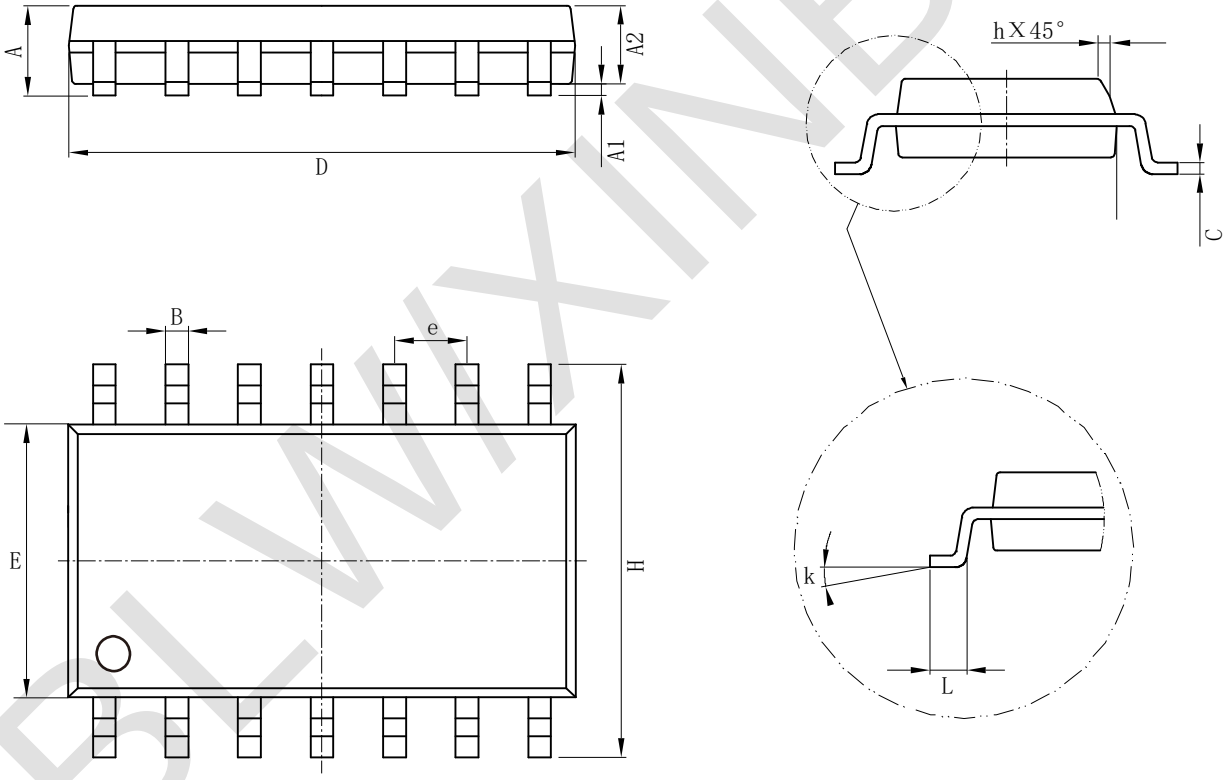






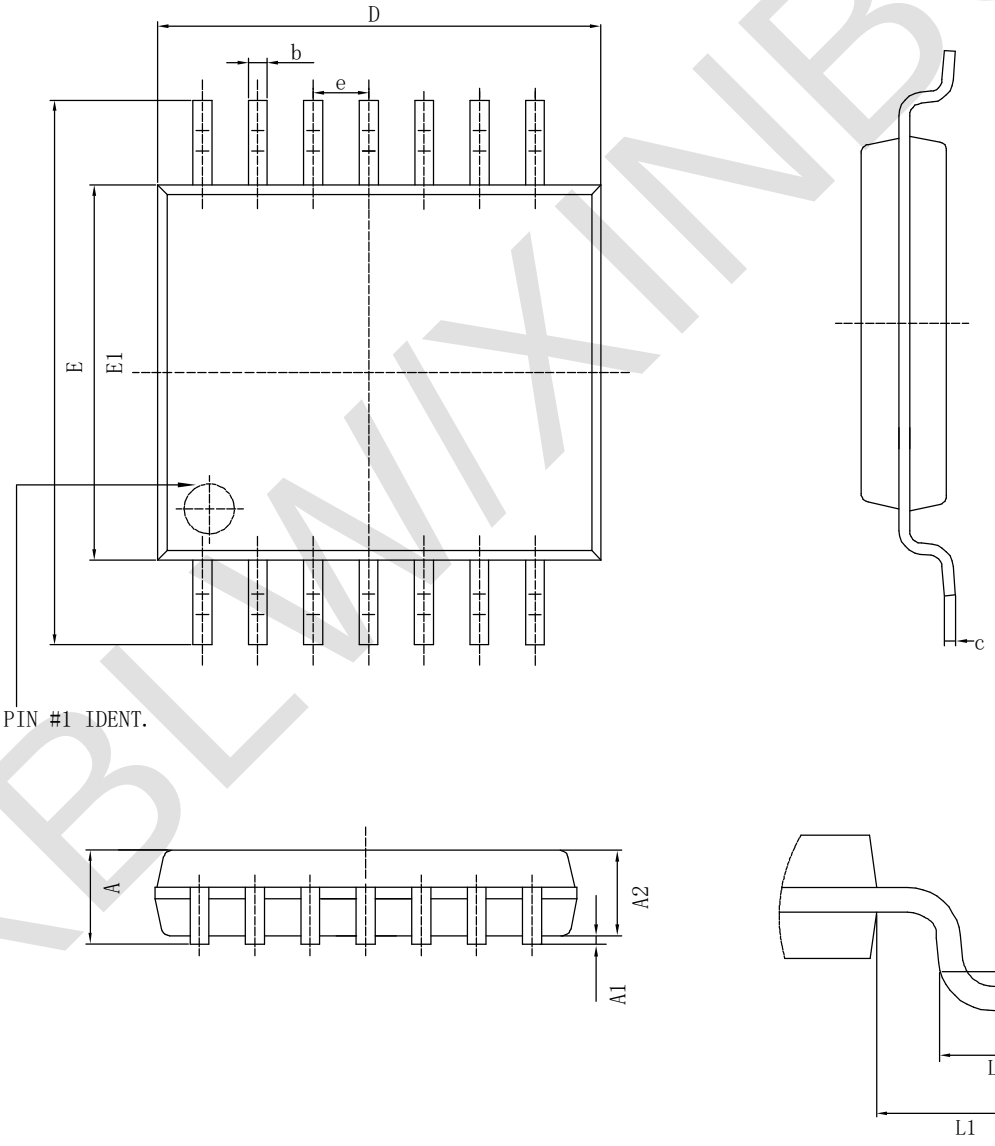
· SOP-14

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	1.350	1.750	A	0.050	0.068
A1	0.100	0.250	A1	0.004	0.009
A2	1.100	1.650	A2	0.040	0.060
B	0.330	0.510	B	0.010	0.020
C	0.190	0.250	C	0.007	0.009
D	8.550	8.750	D	0.330	0.340
E	3.800	4.000	E	0.150	0.150
e	1.27		e	0.05	
H	5.800	6.200	H	0.220	0.240
h	0.250	0.500	h	0.009	0.020
L	0.400	1.270	L	0.015	0.050
k	8° (max)		k	8° (max)	



· TSSOP-14

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.500	E1	0.169	0.176
e	0.65		e	0.0256	
L	0.450	0.750	L	0.018	0.030
L1	1.00		L1	0.039	
k	0°	8°	k	0°	8°



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